# 6-103168-1 <

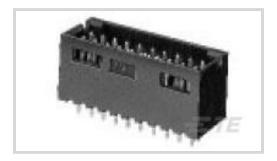
#### AMPMODU | AMPMODU Headers

TE Internal #: 6-103168-1 PCB Mount Header, Vertical, Board-to-Board, 26 Position, 2.54 mm [.1 in] Centerline, Fully Shrouded, Gold, Through Hole - Solder, AMPMODU Headers

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## PCB Connector Assembly Type: PCB Mount Header

PCB Mount Orientation: Vertical

Connector System: Board-to-Board

Number of Positions: 26

Number of Rows: 2

### Features

#### **Product Type Features**

PCB Connector Assembly Type

Connector System

Header Type

PCB Mount Header

Board-to-Board

Fully Shrouded

Connector & Contact	Terminates To
---------------------	---------------

Printed Circuit Board

### **Configuration Features**

Connector Contact Load Condition	Fully Loaded			
PCB Mount Orientation	Vertical			
Number of Positions	26			
Number of Rows	2			
Board-to-Board Configuration	Parallel			
Electrical Characteristics				
Insulation Resistance	5000 ΜΩ			
Dielectric Withstanding Voltage (Max)	750 Vrms			
Body Features				
Connector Profile	Standard			
Primary Product Color	Black			
Contact Features				
Mating Square Post Dimension	.64 mm[.025 in]			

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PCB Contact Termination Area Plating Material Thickness	2.54 – 5.08 μm[100 – 200 μin]			
Contact Shape & Form	Square			
Contact Underplating Material	Nickel			
PCB Contact Termination Area Plating Material	Tin			
Contact Base Material	Phosphor Bronze			
Contact Mating Area Plating Material	Gold			
Contact Mating Area Plating Material Thickness	.762 μm[30 μin]			
Contact Type	Pin			
Contact Current Rating (Max)	3 A			
Termination Features				
Square Termination Post & Tail Dimension	.64 mm[.025 in]			
Termination Post & Tail Length	3.18 mm[.125 in]			
Termination Post & Tail Length Termination Method to Printed Circuit Board				
	3.18 mm[.125 in]			
Termination Method to Printed Circuit Board	3.18 mm[.125 in]			
Termination Method to Printed Circuit Board Mechanical Attachment	3.18 mm[.125 in] Through Hole - Solder			
Termination Method to Printed Circuit Board Mechanical Attachment Mating Retention	3.18 mm[.125 in] Through Hole - Solder With			

Mating Alignment Type	Polarization			
PCB Mount Retention	Without			
PCB Mount Alignment	Without			
Connector Mounting Type	Board Mount			
Housing Features				
Centerline (Pitch)	2.54 mm[.1 in]			
Housing Material	Thermoplastic			
Dimensions				
Row-to-Row Spacing	2.54 mm[.1 in]			
PCB Thickness (Recommended)	1.4 mm[.055 in]			
Usage Conditions				
Housing Temperature Rating	Standard			
Operating Temperature Range	-65 – 105 °C[-85 – 221 °F]			
Operation/Application				
Circuit Application	Signal			

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#### **Industry Standards**

Agency/Standard	CSA				
Approved Standards	CSA LR7189, UL E28476				
UL Flammability Rating	UL 94V-0				
Packaging Features					
Packaging Quantity	64				
Packaging Type	Tray				
Product Compliance					
For compliance documentation, visit the product page on TE.com>					
EU RoHS Directive 2011/65/EU	Compliant				
EU ELV Directive 2000/53/EC	Compliant				
China RoHS 2 Directive MIIT Order No 32, 2016	No Restricted Materials Above Threshold				
EU REACH Regulation (EC) No. 1907/2006	Current ECHA Candidate List: JUNE 2023 (235)				
	Candidate List Declared Against: JUNE				
	2023 (235) Does not contain REACH SVHC				
Halogen Content	BFR/CFR/PVC Free, but Br/Cl >900 ppm in other sources.				

#### Solder Process Capability

Wave solder capable to 240°C

#### Product Compliance Disclaimer

This information is provided based on reasonable inquiry of our suppliers and represents our current actual knowledge based on the information they provided. This information is subject to change. The part numbers that TE has identified as EU RoHS compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, mercury, PBB, PBDE, DBP, BBP, DEHP, DIBP, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2011/65/EU (RoHS2). Finished electrical and electronic equipment products will be CE marked as required by Directive 2011/65/EU. Components may not be CE marked. Additionally, the part numbers that TE has identified as EU ELV compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, and mercury, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2000/53/EC (ELV). Regarding the REACH Regulation, the information TE provides on SVHC in articles for this part number is based on the latest European Chemicals Agency (ECHA) 'Guidance on requirements for substances in articles' posted at this URL: https://echa.europa.eu/guidance-documents/guidance-onreach

## **Compatible Parts**

PCB Mount Header, Vertical, Board-to-Board, 26 Position, 2.54 mm [.1 in] Centerline, Fully Shrouded, Gold, Through Hole - Solder, AMPMODU Headers







## Also in the Series AMPMODU Headers

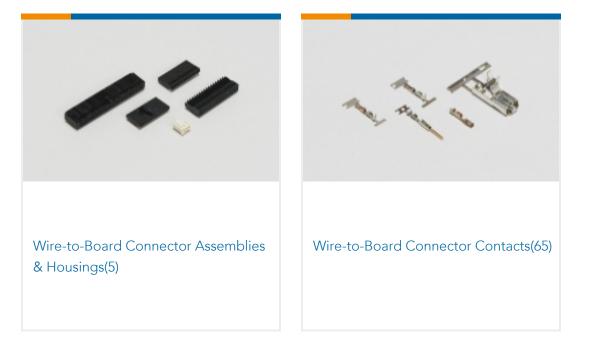






PCB Latches Locks & Retainers(1)

PCB Connector Mounting(1)	PCB Connector Shrouds(1)	PCB Headers & Receptacles(4872)	PCB Latches, Locks & Retainers(1)



## Customers Also Bought



PCB Mount Header, Vertical, Board-to-Board, 26 Position, 2.54 mm [.1 in] Centerline, Fully Shrouded, Gold, Through Hole - Solder, AMPMODU Headers







## Documents

Product Drawings 26 MODII HDR DRST SHRD .100CL

English

CAD Files 3D PDF

3D

Customer View Model ENG\_CVM\_CVM\_6-103168-1\_M.2d\_dxf.zip

English

**Customer View Model** 

ENG\_CVM\_CVM\_6-103168-1\_M.3d\_igs.zip

English

Customer View Model

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ENG_CVM_CVM_6-103168-1_M.3d_stp.zip
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English

By downloading the CAD file I accept and agree to the **Terms and Conditions** of use.

Datasheets & Catalog Pages AMPMODU\_INTERCONNECTION\_SYSTEM\_SECTION5

English

Product Environmental Compliance TE Material Declaration

English